

WHAT IS CLAIMED IS:

1. A package structure of organic electroluminescence (OEL) panel, comprising:
a printed circuit board, having a plurality of solder pads;
at least one OEL panel, disposed over the printed circuit board, wherein the OEL
5 panel comprises:
a substrate;
a plurality of first electrodes, disposed on the substrate, wherein each of
the first electrodes includes a driving region and at least one contact region, and the
contact region is protruding out from the driving region;
10 at least one patterned organic light emitting layer, disposed over the sub-
strate, wherein the patterned organic light emitting layer exposes the contact region;
a plurality of second electrodes, disposed on the patterned organic light
emitting layer; and
a plurality of poly solder interconnections, disposed on the contact re-
15 gions and the second electrodes; and
a plurality of bumps, respectively disposed between the solder pads and the poly
solder interconnections, so as to have electric connection between the OEL panel and
the printed circuit board.
2. The package structure of claim 1, wherein the driving region for each of the
20 first electrodes is a stripe pattern.
3. The package structure of claim 1, wherein each of the second electrodes is a
stripe pattern.

4. The package structure of claim 1, wherein an extending direction of the first electrodes is perpendicular to an extending direction of the second electrodes.

5. The package structure of claim 1, wherein the OEL panel further comprises an electron mobile layer, disposed between the organic light emitting layer and the second electrodes.

6. The package structure of claim 5, wherein the OEL panel further comprises an electron injection layer disposed between the second electrodes and the electron mobile layer.

7. The package structure of claim 1, wherein the OEL panel further comprises a hole mobile layer, disposed between the organic light emitting layer and the first electrodes.

8. The package structure of claim 7, wherein the OEL panel further comprises a hole injection layer disposed between the first electrodes and the electron mobile layer.

9. The package structure of claim 1, wherein the poly solder interconnections includes silver paste.

10. The package structure of claim 1, wherein the printed circuit board includes a ceramic printed circuit board.

11. The package structure of claim 1, wherein the bumps includes gold bumps.

12. The package structure of claim 1, wherein the patterned organic light emitting layer includes a plurality of openings, and the openings expose the contact regions

13. The package structure of claim 1, wherein patterned organic light emitting layer includes a plurality of stripe patterns, whereby the contact regions are exposed.

14. The package structure of claim 1, wherein the poly solder interconnections include a material with a relative low reflowing temperature.

15. The package structure of claim 1, wherein poly solder interconnections are arranged into an array structure.

5 16. A package structure of an organic electroluminescence (OEL) panel, comprising:

 a substrate;

 a plurality of first electrodes, disposed on the substrate, wherein each of the first electrodes includes a driving region and at least one contact region, and the contact re-
10 gion is protruding out from the driving region;

 at least one patterned organic light emitting layer, disposed over the substrate, wherein the patterned organic light emitting layer exposes the contact region;

 a plurality of second electrodes, disposed on the patterned organic light emitting layer; and

15 a plurality of poly solder interconnections, disposed on the contact regions and the second electrodes.

17. The package structure of claim 16, wherein the driving region for each of the first electrodes is a stripe pattern.

20 18. The package structure of claim 16, wherein each of the second electrodes is a stripe pattern.

19. The package structure of claim 16, wherein an extending direction of the first electrodes is perpendicular to an extending direction of the second electrodes.

20. The package structure of claim 16, wherein the OEL panel further comprises an electron mobile layer, disposed between the organic light emitting layer and the second electrodes.

21. The package structure of claim 20, wherein the OEL panel further comprises
5 an electron injection layer disposed between the second electrodes and the electron mobile layer.

22. The package structure of claim 16, wherein the OEL panel further comprises a hole mobile layer, disposed between the organic light emitting layer and the first electrodes.

10 23. The package structure of claim 22, wherein the OEL panel further comprises a hole injection layer disposed between the first electrodes and the electron mobile layer.

24. The package structure of claim 16, wherein the poly solder interconnections includes silver paste.

15 25. The package structure of claim 16, wherein the patterned organic light emitting layer includes a plurality of openings, and the openings expose the contact regions

26. The package structure of claim 16, wherein patterned organic light emitting layer includes a plurality of stripe patterns, whereby the contact regions are exposed.

27. The package structure of claim 16, wherein the poly solder interconnections
20 include a material with a relative low reflowing temperature.

28. The package structure of claim 16, wherein poly solder interconnections are arranged into an array structure.